

HDI PCBs with buildup technology

Provide total solution from PCB layout design,
PCB manufacturing and EMS services on the same site in Vietnam.

From prototype manufacturing to high volume production in our Vietnam Factory

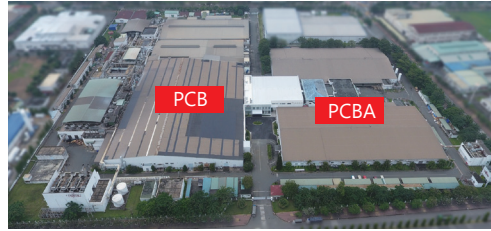
Our factory based in Vietnam allows a one day transportation in the South-East Asia region.

Capacity

PCB Mfg. Capacity 30,000m²/M
PCB assembly 200 million chips/M

Floor area

PCBA 16,000m²
PCB 25,000m²



FICT VIETNAM COMPANY LIMITED



High reliability PCB technology

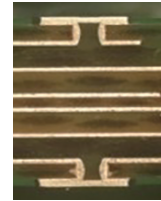
Multi Via technology ensures high density wiring and mounting.

<General Specification>

Structure	Buildup	1-X-1, 2-X-2, 3-X-3, 4-X-4, 5-X-5 (X:2-10)
	Conventional	4 - 20 Layers, Sequential lamination
IVH structure		Filled-Via, Stacked-via structure
Support device pitch		0.3mm Pitch CSP applicable
Low profile application		0.30mm (6L) and 0.58mm (10L) thickness



Any Layer IVH PCB
12L (5-2-5)



Sequential Lamination
8L (2+4+2)

EMS Services with Advanced equipment

- Excellent manufacturing techniques produce high density mounting and high reliable products.
- Lead-free and halogen-free mounting.
- 24 hours per day non-stop operation is available.

CHIP	SSOP	SQFP	BGA/CSP
0402	0.4mm Pitch	0.4mm Pitch	0.4mm Pitch



High-speed chip mounter

Product Application

ECU, ADAS, In-Vehicle Infotainment
Video Camera, Projector, High performance Digital Camera
Mobile Devices
Laptop PC

